

ENDURAPACK EP221

LOW VISCOSITY COLD POUR ENCAPSULATING RESIN

ENDURAPACK EP221 is a cold pour and cold curing, two component epoxy system, exhibiting low shrinkage and good penetration. Applications include the sealing of cable joints, and potting and encapsulation of electrical and electronic componentry. Both resin and hardener are solvent free and can be mixed and cured at room temperature.

Neither component presents any unusual health risk if handled correctly and in adequately ventilated work areas. However, our **Product Safety Data** should always be referred to before use.

Properties of the Components	Resin	Hardener
Type of Compound	Solvent free modified epoxy	Amine
Appearance	Clear straw coloured liquid	Amber liquid
Density at 23 °C	1.12 g/ml	1.05 g/ml
Viscosity at 23 °C	900 - 1300 mPas	100 - 250 mPas
Flash Point	> 200 °C	> 200 °C
Storage	24 months Store in closed containers at below 25 °C away from direct sunlight.	24 months Store in closed containers at below 25 °C away from direct sunlight.

MIX: The resin and hardener must be mixed at room temperature for at least 3 minutes using a wide stirrer to avoid air entrapment.

Properties of the Mix	
Ratio	100 Resin : 44 Hardener by weight 100 Resin : 50 Hardener by volume
Pour time at 20 °C	Approximately 30 minutes
Cure time	24 hours at 20 °C or 2 - 4 hours at room temperature plus a further 2 - 4 hours at 80 °C

TECHNICAL INFORMATION

Typical Properties of the Cured System	Test Measurements
Density	1.12 g/ml
Shrinkage	ca. 2% by volume
Shore hardness	80 Shore D
Tensile strength	55 mPa
Water absorption	< 0.5% (40 °C, 40 days)
Dielectric strength (DIN 53481)	17 - 19 kV/mm
Volume resistivity (DIN 53482)	2 x 10 ¹⁵ ohm-cm
Dielectric constant (DIN 53483)	3.6 @ 50HZ, 25 °C

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